### ircuits and Systems evelopme tainable D



**Resorts World Sentosa Convention Centre** 

# Call for Special Sessions

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems Society and the world's premiere forum for researchers in the active fields of theory, design and implementation of circuits and systems. ISCAS 2024 will be held in Singapore, from May 19 to 22, 2024. Special sessions complement the regular technical program by highlighting new and emerging research topics or innovative applications of established approaches. The topic of a special session proposal should be timely and compelling. While we welcome special sessions in all areas of Circuits and Systems, we are particularly interested in focused research topics, especially those with interdisciplinary and multidisciplinary nature, specifically those related to the conference innovation themes:

- Emerging Technologies
- Big Data Processing
- Smart Systems for
- Automotive
- Artificial Intelligence
- Cognitive Computing and Deep Learning
- Personalized Healthcare
- Systems Sustainable Computing and
- Systems
- Brain: Innovation **NeuroTechnologies** Energy-aware Systems and
- Services
- 5G and Multi-Gigabit

Special sessions can also cover any other area focusing on challenging open problems of relevance in applications. The participation of speakers from the industry is encouraged and will be positively evaluated.

### **Special Sessions Proposals Submission Guidelines**

Please submit proposals (approximately 3 pages) in pdf format by email to the Special Sessions Co-Chairs Mohamad Sawan (sawan@westlake.edu.cn), Volkan Kursun (volkan.kursun@bilkent.edu.tr), Nathalie Deltimple (nathalie.deltimple@imsbordeaux.fr). All papers will be subject to the same peer review process as regular papers. The proposal should include the following information:

### 1. Title and Abstract

Propose a title and an abstract of no more than 200 words that will allow conference attendees to understand the topic and the focus.

### 2. Rationale

Please explain why the topic is novel, why it is relevant to the ISCAS community, and how it fits within the innovation themes listed above.

### 3. Proposed speakers

Provide a list of all talks and authors. Technical sessions are normally expected to have 5 papers. In exceptional cases (like industrial

## **Important Dates:**

Special Sessions Proposal: Special Sessions Proposal Notification: Special Session Papers Submission: Authors' Decision Notification:



talks, or contributions by particularly renowned speakers) it may be possible to have sessions of one talk without an associate paper or a talk which will have a double-time slot for the presentation.

### 4. Biographies

Provide a short bio of the session proposers. An essential aspect in evaluating special session proposals will be the timeliness of the topic, quality/track record of the proposers and speakers, coherence of the session, and expected value added to the overall technical program.

Oct 1, 2023 (extended) Oct 7, 2023 (extended) Oct 31, 2023 (extended)



2024.ieee-iscas.org

**IEEE International Symposium on Circuits and Systems** Singapore, May 19-22, 2024

## **Organizing Committee**

### **General Chair**

Amara Amara. Terre des hommes. Switzerland Yong Lian, York Univ., Canada Bah-Hwee Gwee, NTU, Singapore **TPC Chair** 

Yoshifumi Nishio, Tokushima Univ., Japan Victor Grimblatt, Synopsys, Chile Nam Ling, Santa Clara Univ., USA **Tutorial Chair** 

Massimo Alioto, NUS, Singapore Elena Blokhina, Univ. College Dublin, Ireland Francois Rivet, Univ. of Bordeaux, France **Special Session Chair** 

Mohamad Sawan, Westlake Univ., China Volkan Kursun, Bilkent Univ., Turkey Nathalie Deltimple, Univ. of Bordeaux, France

**Cross-Soc. Special Session Chair** Xinmiao Zhang, OSU, USA

**Embedded Workshop Chair** 

Fakhrul Zaman Rokhani, UPM, Malaysia

Women in CAS (WiCAS) Program Chair Yoko Uwate, Tokushima Univ., Japan

Maria Trocan, ISEP, France Bo Wang, SUTD, Singapore

Young Professional (YP) Program Chair Fidel Makatia, Autodesk, Kenya

## Live Demonstrations Chair

Chao Wang, Huazhong UST, China Deruo Cheng, NTU, Singapore

### **Publicity Chair**

Zhiping Lin, NTU, Singapore Yajun Ha, Shanghai Tech Univ., China Nicole McFarlane, Univ. of Tennessee, USA Wei Liu, Queen Mary Univ. of London, UK

### **International Liaison Chair**

Franco Maloberti, Univ. of Parma, Italy Myung Hoon Sunwoo, Ajou Univ., South Korea Ricardo Reis, UFRGS, Brazil Jose Silva-Martinez, Texas A&M Univ., USA Wei Chen, Fudan Univ., China

## **Publication Chair**

Yongfu Li, Shanghai Jiao Tong Univ., China Kwen Siong Chong, Zero-Error Sys, Singapore **Finance Chair** 

Saihua Xu, NTU, Singapore Tong Ge, NTU, Singapore

## **Local Arrangement Chair**

Jun Wei Lee, DSO, Singapore Kian Ann Ng, Digipen, Singapore Qinglai Liu, NTU, Singapore

### Sponsorship/Exhibition Chair

Xuanyao Fong, NUS, Singapore Anh Tuan Do, A\*STAR, Singapore Zhengguo Li, A\*STAR, Singapore

### **Industry Liaison Chair**

Kiran Gunnam, Western Digital, USA Yi Wang, Continental Automotive, Singapore Rajiv Joshi, IBM, USA Preet Yadav, NXP Semiconductors, India

Yuanjin Zheng, NTU, Singapore

### Webmaster

Fan Yang, Qualcomm, Singapore **Professional Conference Organizer** 

Stanley Teng, A'Tenga C.E., Singapore Mary Teng, A'Tenga C.E., Singapore





Jan 15, 2024